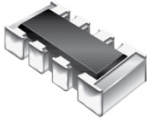


MATERIAL DECLARATION SHEET



Material Number	CAY16A-x4AS			
Product Line	Chip Resistor Array			
Compliance Date	2019/9/9			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Material s Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00731154	Aluminum oxide	1344-28-1	96%	80.42%	83.77%
				Magnesium oxide	14808-82-7	1%	0.84%	
				Silicon dioxide	1309-48-4	3%	2.51%	
2	Conductor Layer	Conductor Layer	0.00010905	Silver	7440-22-4	95%	1.19%	1.25%
				Palladium	7440-05-3	1%	0.01%	
				Glass	65997-17-3	4%	0.05%	
3	Resistive Element	Resistive Element	0.00008402	Ruthenium (IV) oxide	12036-10-1	25%	0.24%	0.96%
				Silver	7440-22-4	40%	0.38%	
				Palladium	7440-5-3	15%	0.14%	
				Lead-containing glass	7439-92-1	20%	0.19%	
4	Over-Coating	Epoxy	0.00012255	Epoxy	25068-38-6	52%	0.73%	1.40%
				Talc	14807-96-6	8%	0.11%	
				Silicon dioxide	60676-86-0	40%	0.56%	
5	Marking	Ink	0.00000437	Epoxy	25085-99-8	55%	0.03%	0.05%
				Barium sulfate	7727-43-7	15%	0.01%	
				Titanium dioxide	13463-67-7	30%	0.02%	
6	End Terminal	Metal	0.00027645	Silver	7440-22-4	80%	2.54%	3.17%
				Epoxy	25085-99-8	20%	0.63%	
7	Ni Plating	Nickel	0.00045055	Nickel	7440-02-0	100%	5.16%	5.16%
8	Sn Plating	Tin	0.00036945	Tin	7440-31-5	100%	4.24%	4.24%

MATERIAL DECLARATION SHEET

Total weight	0.00872798
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This Document was updated on: 2019/9/9

Important remarks: Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I